				I = 1
L	Hits	Search Text	DB -	Time stamp
Number			USPAT;	2002/09/30
1	459667	wafer chip die dice	US-PGPUB	10:30
			USPAT;	2002/09/30
2	4473	(wafer chip die dice) and (quality near10	US-PGPUB	10:31
		test\$3)	USPAT;	2002/09/30
3	2718	((wafer chip die dice) and (quality	US-PGPUB	10:31
		near10 test\$3)) and chip	USPAT;	2002/09/30
4	1339	(((wafer chip die dice) and (quality	US-PGPUB	09:20
		near10 test\$3)) and chip) and memory	USPAT;	2002/09/30
5	702	((((wafer chip die dice) and (quality	US-PGPUB	09:21
		near10 test\$3)) and chip) and memory) and	US-FGFUD	03.21
	,	semiconductor	US-PGPUB	2002/09/30
8	111	((((wafer chip die dice) and (quality	03-16100	09:21
		near10 test\$3)) and chip) and memory) and		03.21
		semiconductor	USPAT	2002/09/30
6	591	((((wafer chip die dice) and (quality	USERI	09:45
	•	near10 test\$3)) and chip) and memory) and		05
		semiconductor	USPAT	2002/09/30
9	39675	semiconductor near10 chip	ODIAL	09:46
		tosts3	USPAT	2002/09/30
10	13489	(semiconductor near10 chip) and test\$3	ODIAL	09:46
		(/ tour house manufil ship) and test\$3)	USPAT	2002/09/30
11	6216	((semiconductor near10 chip) and test\$3) and (dic\$3 singulat\$3 divid\$3)	OBITIE	10:34
	5440	(((semiconductor near10 chip) and test\$3)	USPAT	2002/09/30
12	5443	and (dic\$3 singulat\$3 divid\$3)) and	051111	09:48
		result		
1	79	1	USPAT	2002/09/30
13	19	and (test\$3 near20 result\$3 near50 (dic\$3		10:26
		singulat\$3 divid\$3))		
1	593876		EPO; JPO;	2002/09/30
14	393076	water chip die diec	DERWENT;	10:31
			IBM TDB	
15	414	(wafer chip die dice) and (quality near10	EPO; JPO;	2002/09/30
13	1 313	test\$3)	DERWENT;	10:31
		Cescys	IBM TDB	i
16	246	((wafer chip die dice) and (quality	EPO; JPO;	2002/09/30
1.6	230	near10 test\$3)) and chip	DERWENT;	10:33
		Hearto ceseço, and one	IBM TDB	
17	63267	semiconductor near10 chip	EPO; JPO;	2002/09/30
1 1	03207	Down of the state	DERWENT;	10:33
			IBM_TDB	
18	3803	(semiconductor near10 chip) and test\$3	EPO; JPO;	2002/09/30
10		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT;	10:33
			IBM_TDB	
19	264	((semiconductor near10 chip) and test\$3)	EPO; JPO;	2002/09/30
		and (dic\$3 singulat\$3 divid\$3)	DERWENT;	10:34
			IBM_TDB	